IPC ASSOCIATION ELECTRONIC	Material Compo © Copyright 2005. II international and Pan	PC, Bannockb	urn, Illinois. A	All rights reserved un	nder both	This docume level parts, t	ent is a declara he declaration	tion of the	e substances sses all lowe	within the r level ma	e manufactur terials for w	er listed it hich the m	em. Note: i	f the item is an as r has engineering	sembly with loweresponsibility.
1752-21.1	2-21.1 IPC Web Site for Information on IPC-1752 Standard Form Type http://www.ipc.org/IPC-175x Distribute				*	Declaration Class * Class 6 - RoHS Yes/No, Homogeneous Materials and Mfg Information									
Supplie	r Information														
Company name* Company unique ID					1	Unique ID Authority Response Date*									
onsemi											2023-06-08				
Contact N	Vame		Title - Contact			1	Phone - Contact*				Email - Contact*				
Product-l	Env-Stewards		Product Enviro Compliance				NA				Product-Env-Stewards@onsemi.com				
Authorize	ed Representative*		Title - Representative			]	Phone - Representative*				Email - Representative*				
Product-l	Env-Stewards		Product Envi	iro Compliance	e NA Product-Env-Stewards@onsemi.com					om					
	Requester Item Number Mfr Item		Number	Number Mfr Item Name			Effective Dat	e Versi	ion	Manufacturing Site		V	Veight*	UOM	Unit Type
		STK534UC90A-E 3phase inverter H		3phase inverter HI	С		2023-06-08		,	VN2		1	4100.0	mg	Each
Manufa	acturing Proccess Information	tion													,
Terminal Plating / Grid Array Material Terminal Plating / Grid Array Material			erminal Base	Alloy J-STD-020 MSL Rating Peak Process Body Temperature Max Time at Peak Temperature		ire Numb	per of Reflow Cyc	eles							
	Matte Tin (Sn) - annealed	C	CU Alloy	N	JA.		0		C	30		secono	ls 3		
Comments	S							·							
								·							
or more	information regarding material	composition	please refer to	page 3											

RoHS Material Composition Declaration			Declaration 7	Гуре *	Detailed						
Directive 2015/863/EU amending RoHS Directive 2011/65/EU  RoHS Definition: Quantity limit of 0.01% by mass (1000 PPM) in homogeneous material for Cadmium and quantity limit of 0.1% by mass (1000 PPM) in homogeneous material for: Lead (Pb), Mercury (Hg), Hexavalent Chromium (Cr6+), Polybrominated Biphenyls (PBB), Polybrominated Diphenyl Ethers (PBDE), and Bis(2-ethylhexyl) phthalate (DEHP), Benzyl-butyl phthalate (BBP), Dibutyl phthalate (DBP), Diisobutyl phthalate (DIBP).											
Please indicate whether any homogeneous material (as defined by the RoHS Directive, EU 2011/65/EU and implemented by the laws of the European Union member states) of the part identified on this form contains lead, mercury, cadmium, hexavalentchromium, polybrominated biphenyls and/or polybrominated diphenyl ethers (each a "RoHS restricted substance") in excess of the applicable quantity limit identified above. If a homogeneous material within the part contains a RoHS restricted substance inexcess of an applicable quantity limit, please indicate below which, if any, RoHS exemption you believe may apply. If the part is an assembly with lower level components, the declaration shall encompass all such components. Supplier certifies that it gathered the information it provides in this form using appropriate methods to ensure its accuracy and that such information is true and correct to the best of its knowledge and belief, as of the date that Supplier completes this form. Supplier acknowledges that Company will rely on this certification in determining the compliance of its products with European Union member state laws that implement the RoHS Directive. Company acknowledges that Supplier may have relied on information provided by others in completing this form, and that Supplier may not have independently verified such information. However, in situations where Supplier has not independently verified information provided by others, Supplier agrees that, at a minimum, its uppliers have provided certifications regarding their contributions to the part, and those certifications are at least as comprehensive as the certification in this paragraph. If the Company and the Supplier enter into a written agreement with respect to the identified part, the terms and conditions of that agreement, including any warranty rights and/or remedies provided as part of that agreement, will be the sole and exclusivesource of the Supplier's Standard Terms and Conditions of Sale applicable to such part shall apply.											
RoHS Declaration * 4 - Item(s	does not contain RoHS restricted substances	per the definition above except for sele	ted exemptions	Supplier Acceptance	* Accepted						
Exemption: 7c-I Electrical and electronic co	omponents containing lead in a glass or cera	mic other than dielectric ceramic in	apacitors, e.g. piezoelect	ronic devices, or in a glass or co	eramic matrix compound.						
Exemption List Version	EL-2011/534/EU										
Declaration Signature											
Instructions: Complete all of the required f Requester) and click on Submit Form to ha		ccepted" on the Supplier Acceptance	drop-down. This will dis	play the signature area. Digital	lly sign the declaration (if required by the						
Supplier Digital Signature Ra	astislav Drska	E_									

## **Homogeneous Material Composition Declaration for Electronic Products**

SubItem Instructions: The presence of any JIG Level A or B substances must be declared. [1] indicate the subpart in which the substance is located, [2] provide a description of the homogeneous material [3], enter the weight of the homogeneous material.

Substance Instructions: [A] select the Level (JIG A, JIG B, Requester or Supplier) [B] select the substance category (JIG or Requester) or enter a value (Supplier). [C] select the substance (JIG) or enter the substance and CAS (Other). [D] select a RoHS exemption, if applicable [E] enter the weight of the substance or the PPM concentration [F] Optionally enter the positive (+) and negative (-) tolerance in percent (Note: percent tolerance values are expected to cover a 3 sigma range of distribution unless otherwise noted).

Homogeneous Material	Weight	Unit of Measure	Level	Substance	CAS	Exempt	Weight	Unit of Measure
Chip Parts	48.77	mg	Supplier	Titanium Dioxide (TiO2)	13463-67-7		1.2778	mg
			Supplier	Silver (Ag)	7440-22-4		1.2095	mg
			Supplier	Epoxy resins	129915-35-1		0.4097	mg
			Supplier	Tin (Sn)	7440-31-5		1.3314	mg
			Supplier	Magnesium Monoxide (MgO)	1309-48-4		0.0878	mg
			Supplier	Silica Amorphous (SiO2)	7631-86-9		0.834	mg
			Supplier	Ceramic	12013-47-7, 12047- 27-7		6.6474	mg
			Supplier	Phenolic resins	Proprietary Data		0.0585	mg
			Supplier	Palladium (Pd)	7440-05-3		0.0195	mg
			Supplier	Aluminum Trioxide (Al2O3)	1344-28-1		30.5203	mg
			В	Nickel (Ni)	7440-02-0		3.0335	mg
			A	Lead Oxide (PbO)	1317-36-8	7c	0.0585	mg
			Supplier	Chromium Trioxide (Cr2O3)	1308-38-9		0.0049	mg
			Supplier	Copper (Cu)	7440-50-8		2.8726	mg
			Supplier	Silica Crystalline (SiO2)	14808-60-7		0.4048	mg
Die	33.44	mg	Supplier	Silicon (Si)	7440-21-3		33.44	mg
Die Attach	2.03	mg	Supplier	Silver (Ag)	7440-22-4		1.4642	mg
			Supplier	Other Epoxy resins	Proprietary Data		0.3536	mg
			Supplier	Tin (Sn)	7440-31-5		0.1192	mg
			Supplier	Other Metal Oxide	Proprietary Data		0.0818	mg
			В	Antimony (Sb)	7440-36-0		0.0112	mg
Heat Sink	864.0	mg	Supplier	Silver (Ag)	7440-22-4		138.24	mg
			Supplier	Copper (Cu)	7440-50-8		725.7599	mg
Lead Frame	523.74	mg	Supplier	Tin (Sn)	7440-31-5		0.3142	mg
			Supplier	Copper (Cu)	7440-50-8		523.4257	mg
Mold Compound-Black	8485.29	mg		Brominated epoxy resin	proprietary data		21.2132	mg
			Supplier	Phenolic Resin	Proprietary Data		439.538	mg
			В	Antimony Trioxide (Sb2O3)	1309-64-4		15.2735	mg
			Supplier	Carbon Black (C)	1333-86-4		34.7897	mg
			Supplier	Aluminum Hydroxide (Al(OH)3)	21645-51-2		594.8188	mg
			Supplier	Fused Silica (SiO2)	60676-86-0		5573.1387	mg

			Supplier	Ortho-Cresol Novolac Resin	29690-82-2	934.2305	mg
			Supplier	Silica Crystalline (SiO2)	14808-60-7	872.2878	mg
Plating	1.05	mg	Supplier	Tin (Sn)	7440-31-5	0.6499	mg
			В	Nickel (Ni)	7440-02-0	0.4	mg
RDL	3991.0	mg	В	Nickel (Ni)	7440-02-0	2470.429	mg
			Supplier	Gold (Au)	7440-57-5	21.5514	mg
			Supplier	Copper (Cu)	7440-50-8	7.5829	mg
			Supplier	Aluminum (Al)	7429-90-5	1491.4366	mg
Solder Ball	77.8	mg	Supplier	Silver (Ag)	7440-22-4	2.1706	mg
			Supplier	Tin (Sn)	7440-31-5	75.1704	mg
			В	Antimony (Sb)	7440-36-0	0.07	mg
			Supplier	Copper (Cu)	7440-50-8	0.389	mg
Wire Bond	72.88	mg	Supplier	Silicon (Si)	7440-21-3	0.0073	mg
			Supplier	Aluminum (Al)	7429-90-5	72.8727	mg